

# EQRE13A2J-100.000M

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## REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 2, 2017)


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## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVDS (DS) 3.3Vdc 6 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 100.000MHz  $\pm$ 100ppm over 0°C to +70°C

## ELECTRICAL SPECIFICATIONS

<b>Nominal Frequency</b>	100.000MHz
<b>Frequency Tolerance/Stability</b>	$\pm$ 100ppm Maximum over 0°C to +70°C (Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
<b>Aging at 25°C</b>	$\pm$ 3ppm Maximum First Year
<b>Supply Voltage</b>	3.3Vdc $\pm$ 5%
<b>Input Current</b>	30mA Maximum
<b>Output Voltage Logic High (Voh)</b>	1.43Vdc Typical, 1.6Vdc Maximum
<b>Output Voltage Logic Low (Vol)</b>	1.1Vdc Typical, 0.9Vdc Minimum
<b>Differential Output Error (dVod)</b>	50mV Maximum
<b>Differential Output Voltage (Vod)</b>	247mV Minimum, 330mV Typical, 454mV Maximum
<b>Offset Voltage (Vos)</b>	1.125V Minimum, 1.250V Typical, 1.375V Maximum
<b>Rise/Fall Time</b>	400pSec Maximum (Measured at 20% to 80% of Waveform)
<b>Duty Cycle</b>	50 $\pm$ 5(%) (Measured at 50% of Waveform)
<b>Offset Error (dVos)</b>	50mV Maximum
<b>Load Drive Capability</b>	100 Ohms Between Output and Complementary Output
<b>Output Logic Type</b>	LVDS
<b>Phase Noise</b>	All Values are Typical -50dBc/Hz at 10Hz Offset -82dBc/Hz at 100Hz Offset -116dBc/Hz at 1kHz Offset -138dBc/Hz at 10kHz Offset -144dBc/Hz at 100kHz Offset -149dBc/Hz at 1MHz Offset -155dBc/Hz at 10MHz Offset -155dBc/Hz at 20MHz Offset
<b>Output Control Function</b>	Standby (on Pad 1)
<b>Output Control Input Voltage Logic High (Vih)</b>	70% of Vdd Minimum or No Connect to Enable Output and Complementary Output
<b>Output Control Input Voltage Logic Low (Vil)</b>	30% of Vdd Maximum to Disable Output and Complementary Output (High Impedance)
<b>Standby Output Enable Time</b>	10mSec Maximum
<b>Standby Output Disable Time</b>	200nSec Maximum
<b>Standby Current</b>	10 $\mu$ A Maximum (Without Load)
<b>RMS Phase Jitter</b>	200fSec Maximum (Fj=12kHz to 20MHz (Random))
<b>Period Jitter (Deterministic)</b>	0.2pSec Typical
<b>Period Jitter (Random)</b>	1.0pSec Typical
<b>Period Jitter (One Sigma)</b>	1.5pSec Typical
<b>Period Jitter (tp-p)</b>	40pSec Maximum
<b>Start Up Time</b>	10mSec Maximum
<b>Storage Temperature Range</b>	-55°C to +125°C

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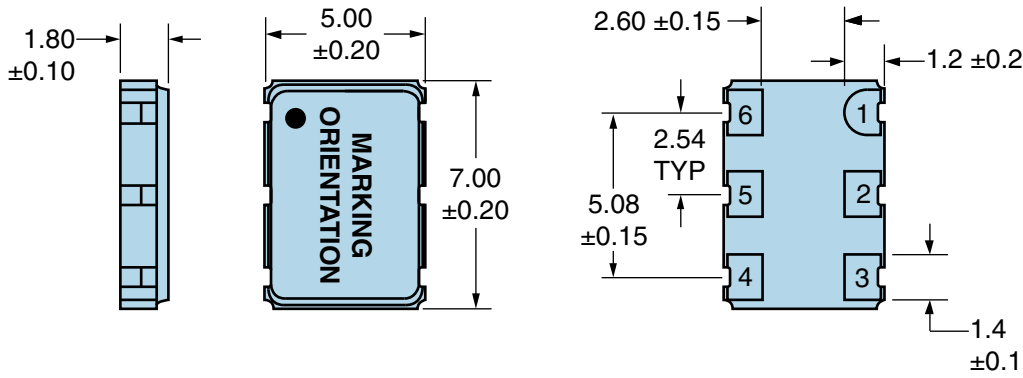
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## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

<b>ESD Susceptibility</b>	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
<b>Fine Leak Test</b>	MIL-STD-883, Method 1014, Condition A
<b>Flammability</b>	UL94-V0
<b>Gross Leak Test</b>	MIL-STD-883, Method 1014, Condition C
<b>Mechanical Shock</b>	MIL-STD-883, Method 2002, Condition B
<b>Moisture Resistance</b>	MIL-STD-883, Method 1004
<b>Moisture Sensitivity</b>	J-STD-020, MSL 1
<b>Resistance to Soldering Heat</b>	MIL-STD-202, Method 210, Condition K
<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

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### MECHANICAL DIMENSIONS (all dimensions in millimeters)

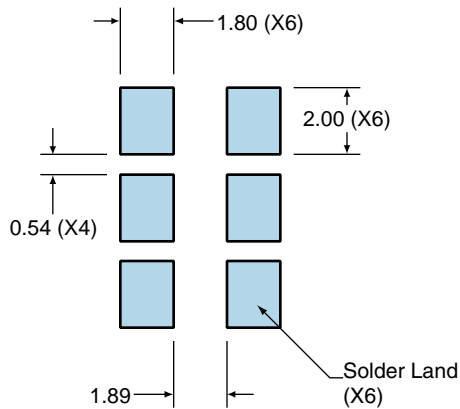


PIN	CONNECTION
1	Standby
2	No Connect
3	Case Ground
4	Output
5	Complementary Output
6	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	100.00M
3	XXXXX XXXXX=Ecliptek Manufacturing Identifier

### Suggested Solder Pad Layout

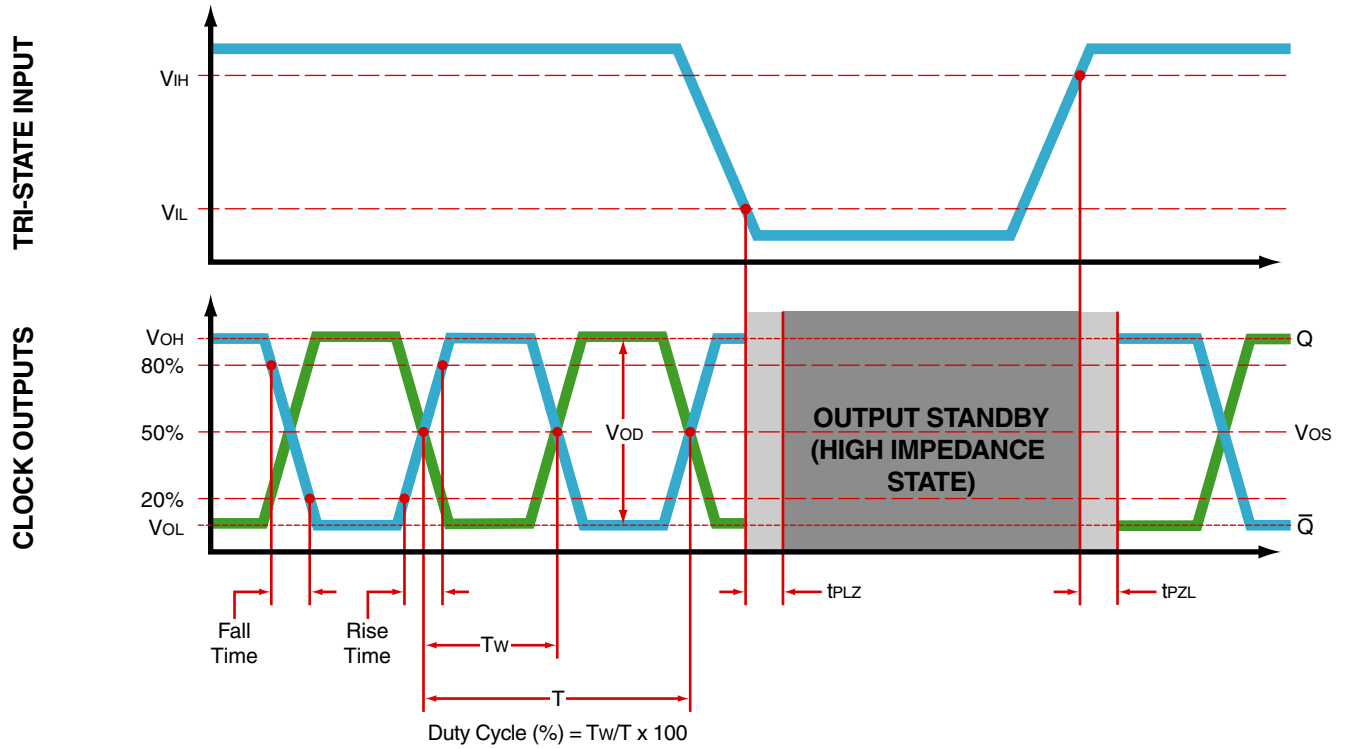
All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

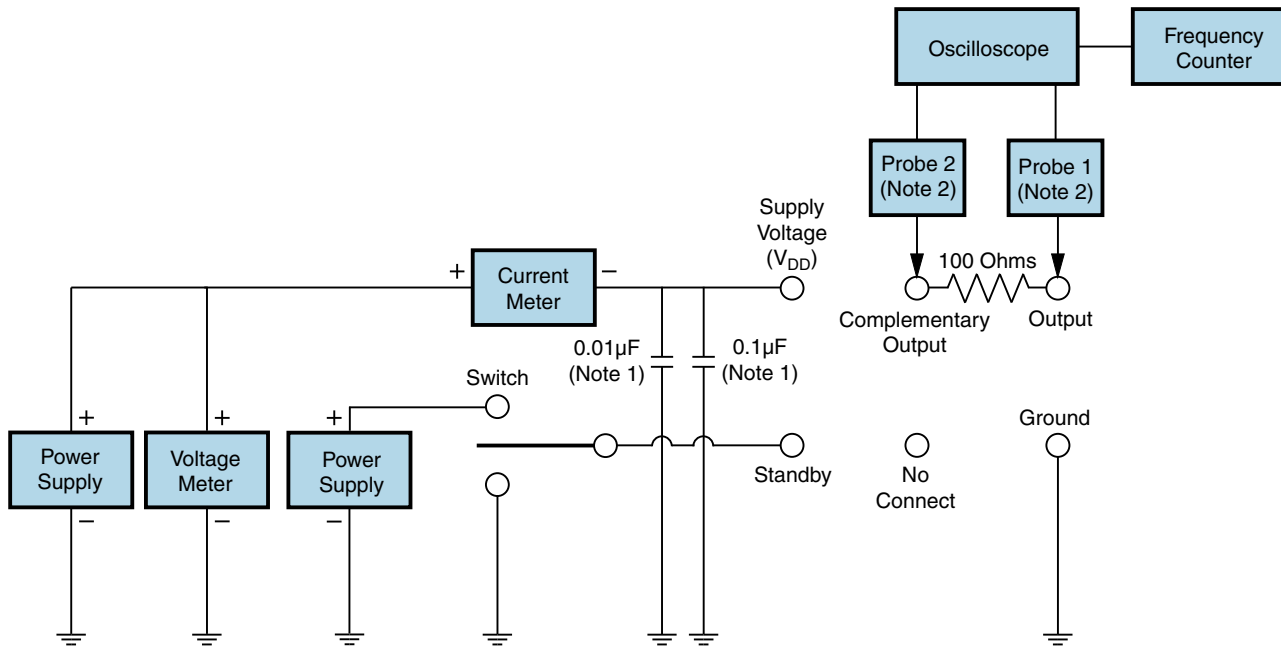
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### OUTPUT WAVEFORM & TIMING DIAGRAM



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## Test Circuit for Standby (Pad 1) and Complementary Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>500MHz) passive probe is recommended.

Note 3: Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	150°C
- Temperature Typical ( $T_s$ TYP)	175°C
- Temperature Maximum ( $T_s$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
<b>Ramp-up Rate (TL to TP)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
<b>Peak Temperature (TP)</b>	240°C Maximum
<b>Target Peak Temperature (TP Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (tp)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)